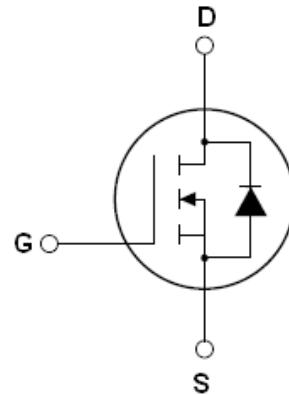


## N-Channel Super Junction Power MOSFET III

### General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

$V_{DS}$	600	V
$R_{DS(ON)TYP}$	500	mΩ
$I_D$	7	A



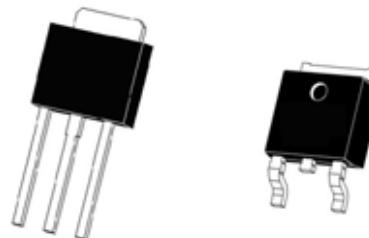
### Features

- New technology for high voltage device
- Low on-resistance and low conduction losses
- Small package
- Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested
- ROHS compliant
- Halogen-free

### Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

**Schematic diagram**



**TO-251**

**TO-252**

### Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage ( $V_{GS}=0\text{V}$ )	$V_{DS}$	600	V
Gate-Source Voltage ( $V_{DS}=0\text{V}$ ), AC ( $f>1\text{ Hz}$ )	$V_{GS}$	$\pm 30$	V
Continuous Drain Current at $T_c=25^\circ\text{C}$	$I_D$ (DC)	7	A
Pulsed drain current (Note 1)	$I_{DM}$ (pulse)	21	A
Maximum Power Dissipation( $T_c=25^\circ\text{C}$ )	$P_D$	63	W
Single pulse avalanche energy (Note 2)	$E_{AS}$	162	mJ
Avalanche current (Note 1)	$I_{AR}$	1.4	A
Repetitive Avalanche energy , $t_{AR}$ limited by $T_{jmax}$ (Note 1)	$E_{AR}$	0.2	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55...+150	°C

## Thermal Characteristic

Thermal Resistance,Junction-to-Case <sup>(Note 2)</sup>	R <sub>θJC</sub>	2.0	°C /W
Thermal Resistance,Junction-to-Ambient <sup>(Note 2)</sup>	R <sub>θJA</sub>	62	°C /W

## Electrical Characteristics ( $T_c=25^\circ\text{C}$ unless otherwise noted)

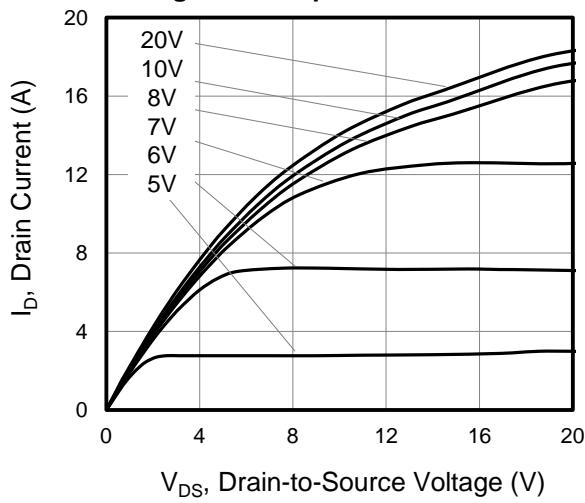
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	600	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =600V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.5	-	4.0	V
Drain-Source On-State Resistance	R <sub>Ds(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =3A	-	500	580	m
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =3A	-	5.0	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V, F=1.0MHz	-	587	-	PF
Output Capacitance	C <sub>oss</sub>		-	31	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	4.0	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> =400V, I <sub>D</sub> =7A V <sub>GS</sub> =10V, R <sub>GEN</sub> =25	-	39	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	25	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	100	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	18	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =480V, I <sub>D</sub> =7A, V <sub>GS</sub> =10V	-	14.5	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	3.0	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	5.2	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>s</sub> =7A	-	0.9	1.2	V
Diode Forward Current <sup>(Note 2)</sup>	I <sub>s</sub>		-	-	6.3	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, IF = I <sub>s</sub> di/dt = 100A/μs(Note3)	-	250	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>		-	2.1	-	nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

### Notes:

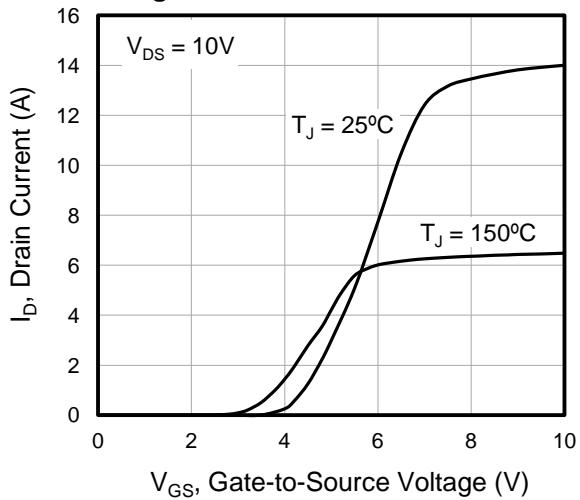
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. EAS condition: T<sub>j</sub>=25°C, V<sub>DD</sub>=50V, I<sub>AS</sub>=1.4A, R<sub>g</sub>=25Ω

## RATING AND CHARACTERISTICS CURVES (RM7N600LD(IP))

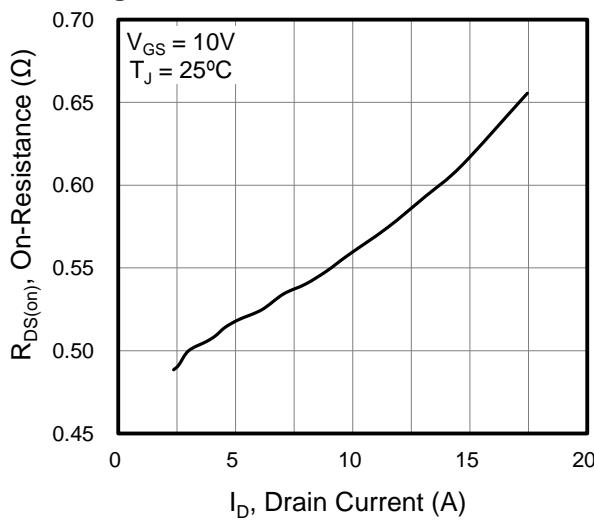
**Figure 1. Output Characteristics**



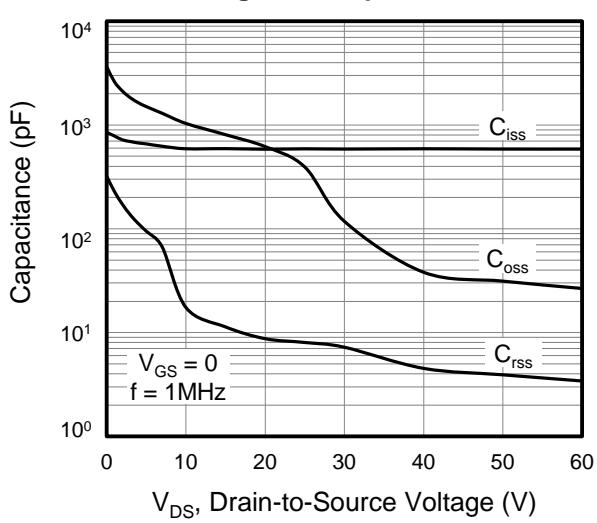
**Figure 2. Transfer Characteristics**



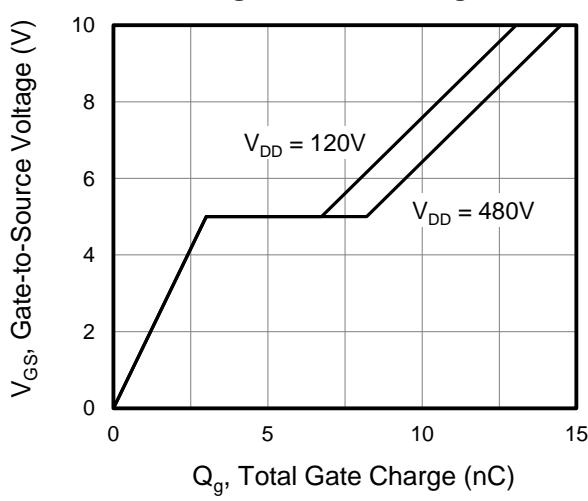
**Figure 3. On-Resistance vs. Drain Current**



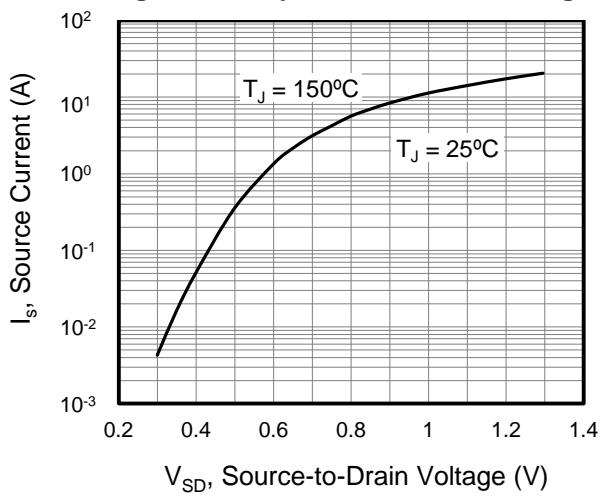
**Figure 4. Capacitance**



**Figure 5. Gate Charge**

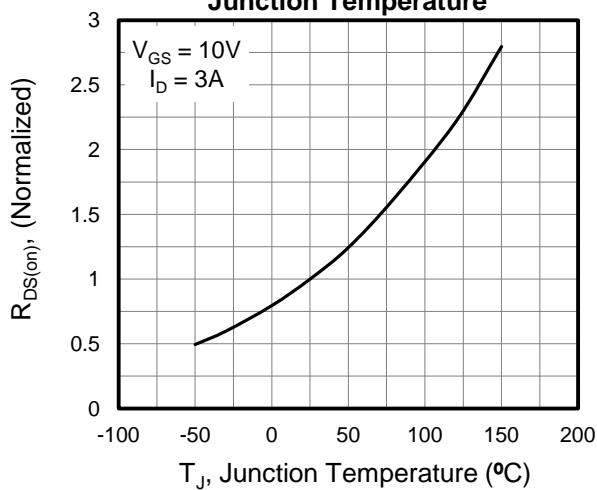


**Figure 6. Body Diode Forward Voltage**

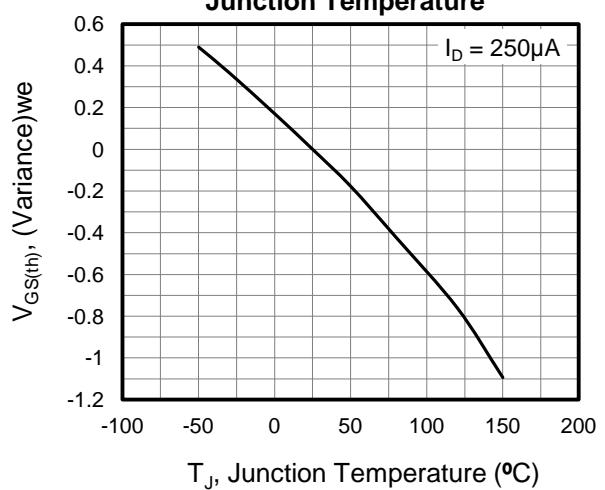


## RATING AND CHARACTERISTICS CURVES (RM7N600LD(IP))

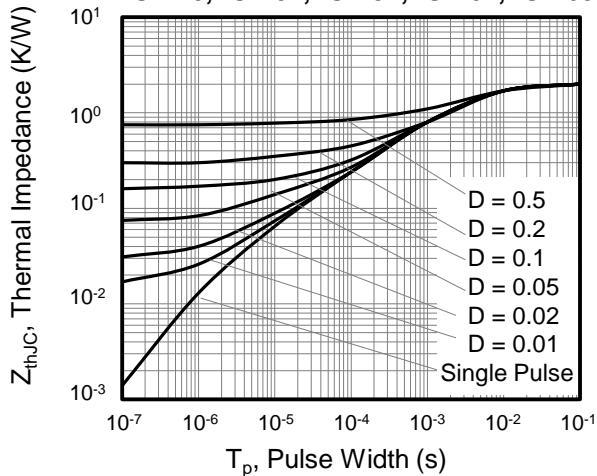
**Figure 7. On-Resistance vs. Junction Temperature**



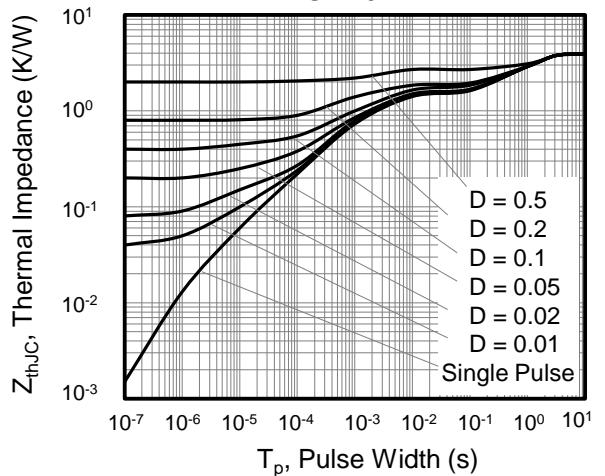
**Figure 8. Threshold Voltage vs. Junction Temperature**



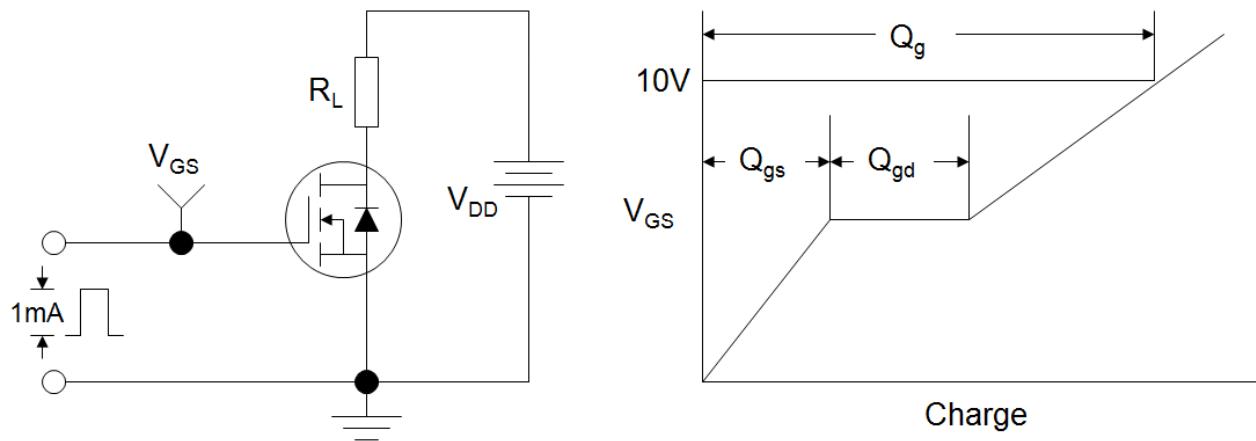
**Figure 9. Transient Thermal Impedance TO-220,TO-251,TO-252,TO-262,TO-263**



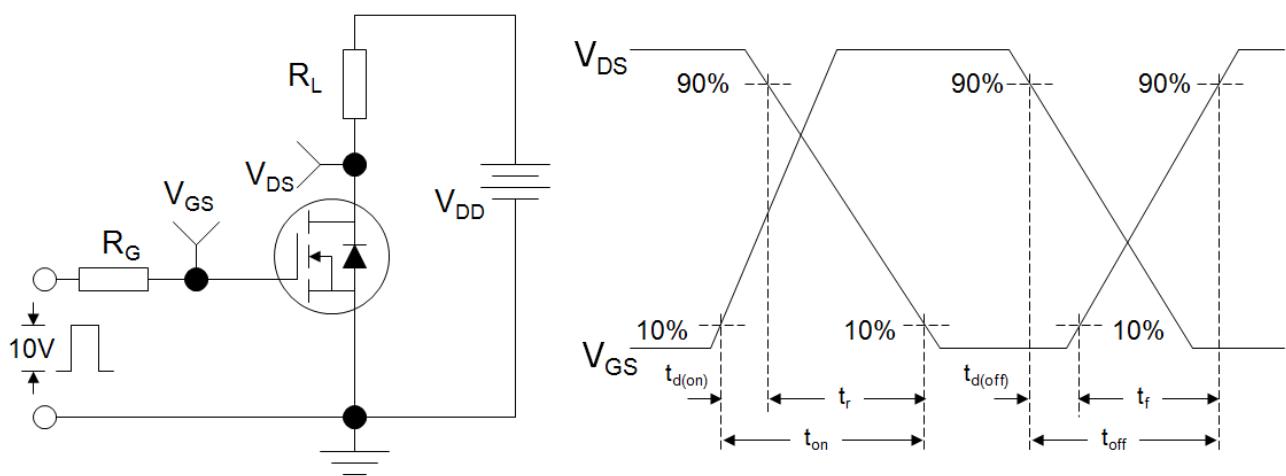
**Figure 10. Transient Thermal Impedance TO-220F**



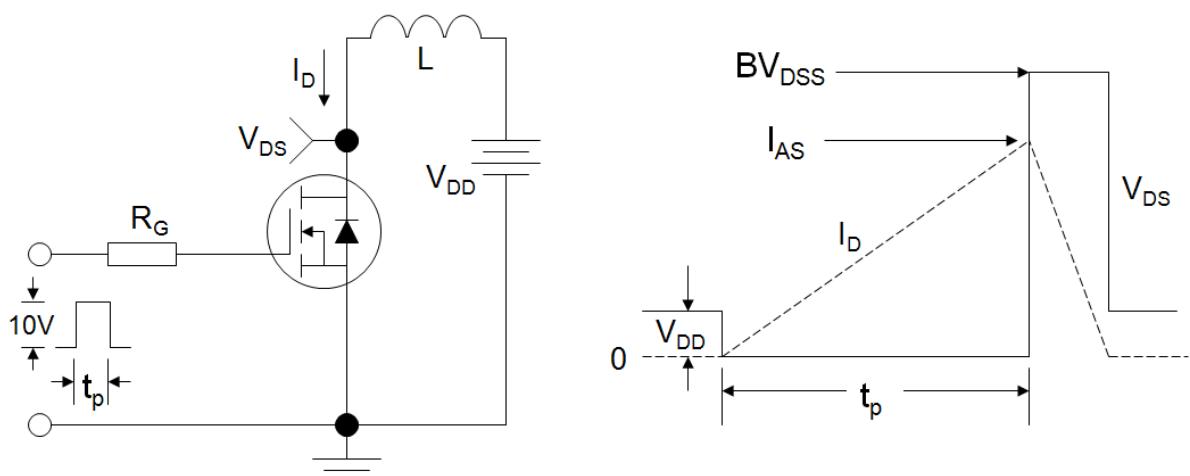
**Figure A: Gate Charge Test Circuit and Waveform**



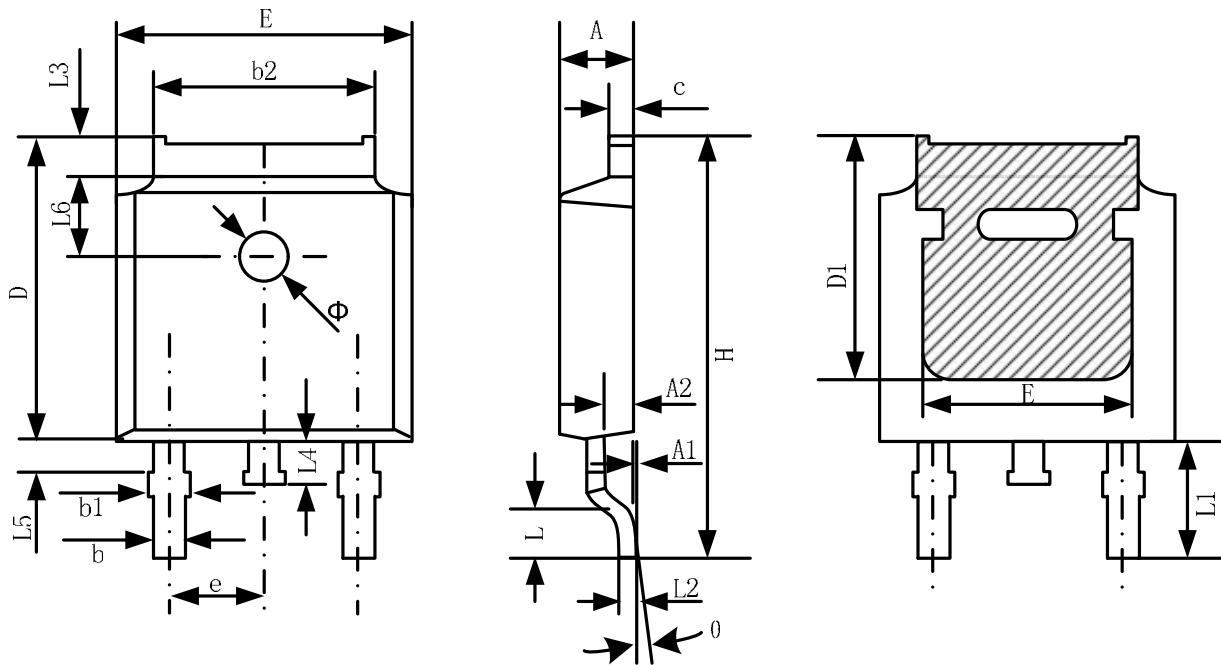
**Figure B: Resistive Switching Test Circuit and Waveform**



**Figure C: Unclamped Inductive Switching Test Circuit and Waveform**

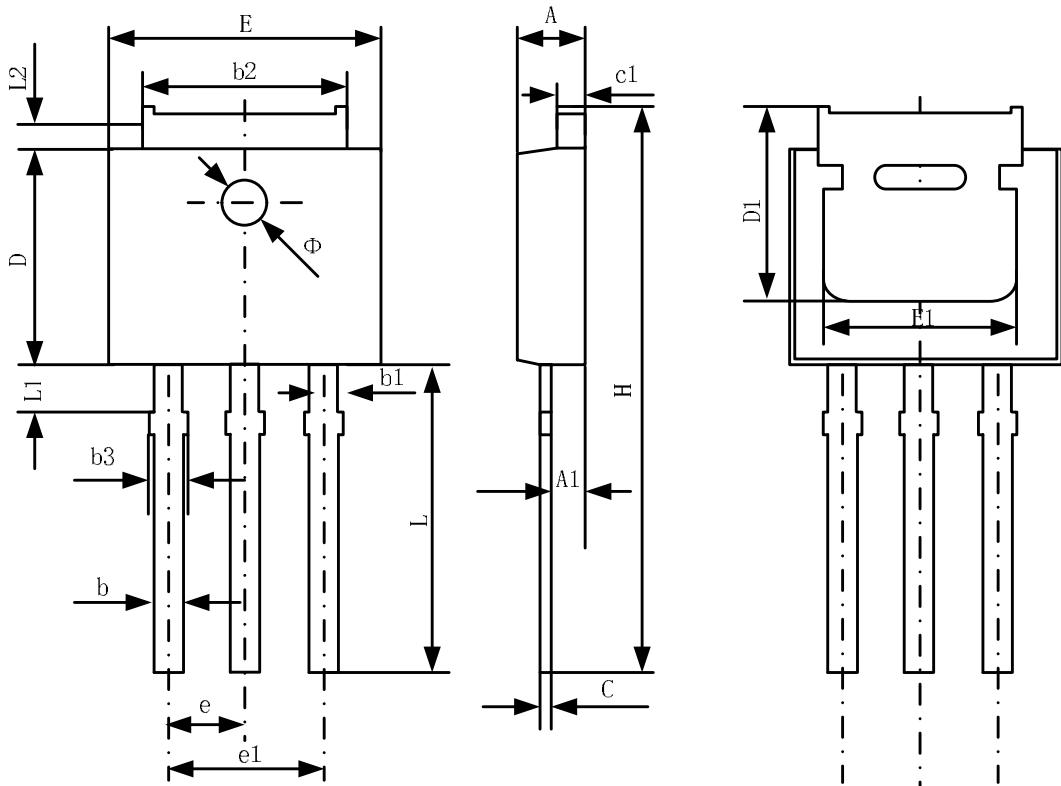


## TO-252-2 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.38	0.087	0.094
A1	0.00	0.10	0.000	0.004
A2	0.90	1.10	0.035	0.043
b	0.72	0.85	0.028	0.033
b1	0.72	0.90	0.028	0.035
b2	5.13	5.46	0.202	0.215
c	0.47	0.60	0.019	0.024
D	6.00	6.20	0.236	0.244
D1	5.25	--	0.207	--
E	6.50	6.70	0.256	0.264
E1	4.70	--	0.185	--
e	2.19	2.39	0.086	0.094
H	9.80	10.40	0.386	0.409
L	1.40	1.70	0.055	0.067
L1	2.90 REF		0.114 REF	
L2	0.508 BSC		0.020 BSC	
L3	0.90	1.25	0.035	0.049
L4	0.60	1.00	0.024	0.039
L5	0.15	0.75	0.006	0.030
L6	1.80 REF		0.071 REF	
$\Phi$	1.20	1.40	0.047	0.055
$\theta$	0°	8°	0°	8°

# TO-251 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.35	0.087	0.093
A1	0.90	1.10	0.035	0.043
b	0.56	0.69	0.022	0.027
b1	0.77	0.90	0.030	0.035
b2	5.23	5.43	0.206	0.214
b3		1.05	0.000	0.041
C	0.46	0.59	0.018	0.023
c1	0.46	0.59	0.018	0.023
D	6.00	6.20	0.236	0.244
D1	5.20		0.205	
E	6.50	6.70	0.256	0.264
E1	4.60	5.00	0.181	
e	2.24	2.34	0.088	0.092
e1	4.47	4.67	0.176	0.184
H	16.18	16.78	0.637	0.661
L	9.00	9.60	0.354	0.378
L1	0.95	1.35	0.037	0.053
L2	0.90	1.25	0.035	0.049

## **DISCLAIMER NOTICE**

Rectron Inc reserves the right to make changes without notice to any product specification herein, to make corrections, modifications, enhancements or other changes. Rectron Inc or anyone on its behalf assumes no responsibility or liability for any errors or inaccuracies. Data sheet specifications and its information contained are intended to provide a product description only. "Typical" parameters which may be included on RECTRON data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. Rectron Inc does not assume any liability arising out of the application or use of any product or circuit.

Rectron products are not designed, intended or authorized for use in medical, life-saving implant or other applications intended for life-sustaining or other related applications where a failure or malfunction of component or circuitry may directly or indirectly cause injury or threaten a life without expressed written approval of Rectron Inc. Customers using or selling Rectron components for use in such applications do so at their own risk and shall agree to fully indemnify Rectron Inc and its subsidiaries harmless against all claims, damages and expenditures.